

ABSTRACT

Method and apparatus are provided for thermally coupling one or more electronic devices to a heatsink. The apparatus comprises a heatsink having a substantially planar upper surface, a wiring board (PWB) with a through-hole for receiving the device such that a principal face thereof is in thermal contact with the heatsink, its electrical leads are captured between at least a portion of the wiring board and the heatsink, and a top of the device protrudes through the PWB. The method comprises placing the device in the through-hole with its base exposed on and protruding from the underside of the PWB, attaching its electrical leads to contacts on the wiring board and pressing the PWB toward the heatsink with the leads captured there between. An electrically insulating thermally conducting layer is desirably placed between the wiring board and the heatsink.